

Winding Type Inductor

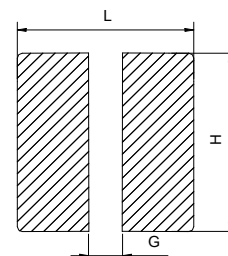
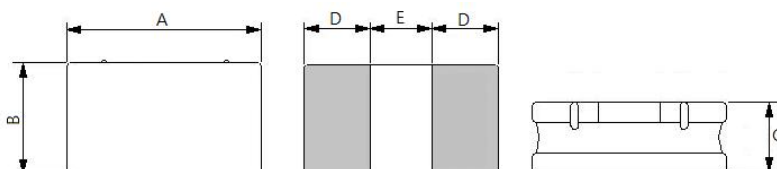
HPC201210MF-SERIES

1. Features

1. This specification applies Low Profile and Low DCR .
2. It can be applied to the Bluetooth device and other electronic equipment.
3. 100% Lead (Pb) & Halogen-Free and RoHS compliant.
4. Operating temperature -40~+125°C (Including self - temperature rise)



Recommended PC Board Pattern

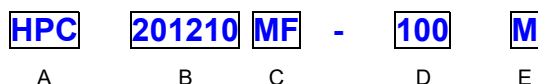


Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
HPC201210MF	2.0 ± 0.2	1.2 ± 0.2	1.0 Max	0.70 ref	0.60 ref

Units: mm

L(mm)	G(mm)	H(mm)
2.40	0.60	1.44

3. Part Numbering



- A: Series
 B: Dimension
 C: Lead Free Ferrite
 D: Inductance 100=10.0uH
 E: Inductance Tolerance K=± 10%, L=± 15%, M=± 20%, Y=± 30%.

4. Specification

Part Number	Inductance (uH)±20% @ 0 A	Test Frequency (Hz)	I rms (A)		I sat (A)		DCR (Ω)	
			Typ	Max	Typ	Max	Typ	Max
HPC201210MF-1R0M	1.00	1V/1M	2.00	1.70	1.10	0.90	0.070	0.084
HPC201210MF-2R2M	2.20	1V/1M	1.25	1.10	0.70	0.65	0.160	0.192
HPC201210MF-4R7M	4.70	1V/1M	1.00	0.85	0.40	0.35	0.320	0.384
HPC201210MF-100M	10.0	1V/1M	0.80	0.65	0.30	0.25	0.600	0.720

Note:

Heat Rated Current (Irms) will cause the coil temperature rise approximately Δt of 40°C.

Saturation Current (Isat) will cause L0 to drop approximately 30%.

Rated DC current: The lower value of Irms and Isat.

Measurement board data

Irms

Material : FR4

Board dimensions : 100 X 50 X 1.6t mm

Pattern dimensions: 45 X 30 mm (Double side board)

Pattern thickness : 50 μm

10. Typical Performance Curves

